ABSTRACT

COATING FOR ENHANCING ADHESION OF MOLDING COMPOUND TO SEMICONDUCTOR DEVICES

A method is provided for enhancing adhesion between a molding compound and a semiconductor device comprising a semiconductor chip attached on a carrier, such as a lead frame, by coating the semiconductor device with a polymer primer prior to molding the semiconductor device. Such coating may be performed by dipping, dripping or spraying the semiconductor device in or with a polymer solution.

(FIG. 2)